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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Obsolete
Core Processor	MIPS-II
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	133MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/idt79rc32v333-133dh

- ◆ 2KB of 2-way set associative data cache, capable of write-back and write-through operation.
- ◆ Cache locking per line to speed real-time systems and critical system functions
- ◆ On-chip TLB to enable multi-tasking in modern operating systems
- ◆ EJTAG interface to enable sophisticated low-cost in-circuit emulation.

Synchronous-DRAM Interface

The RC32333 integrates a SDRAM controller which provides direct control of system SyncDRAM running at speeds to 75MHz.

Key capabilities of the SDRAM controller include:

- ◆ Direct control of 4 banks of SDRAM (up to 2 64-bit wide DIMMs)
- ◆ On-chip page comparators optimize access latency.
- ◆ Speeds to 75MHz
- ◆ Programmable address map.
- ◆ Supports 16, 64, 128, 256, or 512Mb SDRAM devices
- ◆ Automatic refresh generation driven by on-chip timer
- ◆ Support for discrete devices, SODIMM, or DIMM modules.

Thus, systems can take advantage of the full range of commodity memory that is available, enabling system optimization for cost, real-estate, or other attributes.

Local Memory and I/O Controller

The local memory and I/O controller implements direct control of external memory devices, including the boot ROM as well as other memory areas, and also implements direct control of external peripherals.

The local memory controller is highly flexible, allowing a wide range of devices to be directly controlled by the RC32333 processor. For example, a system can be built using an 8-bit boot ROM, 16-bit FLASH cards (possibly on PCMCIA), a 32-bit SRAM or dual-port memory, and a variety of low-cost peripherals.

Key capabilities include:

- ◆ Direct control of EPROM, FLASH, RAM, and dual-port memories
- ◆ 6 chip-select outputs, supporting up to 8MB per memory space
- ◆ Supports mixture of 8-, 16-, and 32-bit wide memory regions
- ◆ Flexible timing protocols allow direct control of a wide variety of devices
- ◆ Programmable address map for 2 chip selects
- ◆ Automatic wait state generation.

PCI Bus Bridge

In order to leverage the wide availability of low-cost peripherals for the PC market as well as to simplify the design of add-in functions, the RC32333 integrates a full 32-bit PCI bus bridge. Key attributes of this bridge include:

- ◆ 50 MHz operation
- ◆ PCI revision 2.2 compliant
- ◆ Programmable address mappings between CPU/Local memory and PCI memory and I/O
- ◆ On-chip PCI arbiter
- ◆ Extensive buffering allows PCI to operate concurrently with local memory transfers
- ◆ Selectable byte-ordering swapper.

On-Chip DMA Controller

To minimize CPU exception handling and maximize the efficiency of system bandwidth, the RC32333 integrates a very sophisticated 4-channel DMA controller on chip.

The RC32333 DMA controller is capable of:

- ◆ Chaining and scatter/gather support through the use of a flexible, linked list of DMA transaction descriptors
- ◆ Capable of memory->memory, memory->I/O, and PCI->memory DMA
- ◆ Unaligned transfer support
- ◆ Byte, halfword, word, quadword DMA support.

On-Chip Peripherals

The RC32333 also integrates peripherals that are common to a wide variety of embedded systems.

- ◆ Single 16550 compatible UART.
- ◆ SPI master mode interface for direct interface to EEPROM, A/D, etc.
- ◆ Interrupt Controller to speed interrupt decode and management
- ◆ Four 32-bit on-chip Timer/Counters
- ◆ Programmable I/O module

Debug Support

To facilitate rapid time to market, the RC32333 provides extensive support for system debug.

First and foremost, this product integrates an EJTAG in-circuit emulation module, allowing a low-cost emulator to interoperate with programs executing on the controller. By using an augmented JTAG interface, the RC32333 is able to reuse the same low-cost emulators developed around the RC32364 CPU.

Pin Description Table

The following table lists the pins provided on the RC32333. Note that those pin names followed by “_n” are active-low signals. All external pull-ups and pull-downs require 10 kΩ resistor.

Name	Type	Reset State Status	Drive Strength Capability	Description																														
Local System Interface																																		
mem_data[31:0]	I/O	Z	High	Local system data bus Primary data bus for memory. I/O and SDRAM.																														
mem_addr[22:2]	I/O	[22:10] Z [9:2] L	[22:17] Low [16:2] High	<p>Memory Address Bus These signals provide the Memory or DRAM address, during a Memory or DRAM bus transaction. During each word data, the address increments either in linear or sub-block ordering, depending on the transaction type. The table below indicates how the memory write enable signals are used to address discreet memory port width types.</p> <table border="1"> <thead> <tr> <th>Port Width</th> <th>Pin Signals</th> <th>mem_we_n[3]</th> <th>mem_we_n[2]</th> <th>mem_we_n[1]</th> <th>mem_we_n[0]</th> </tr> </thead> <tbody> <tr> <td>DMA (32-bit)</td> <td>mem_we_n[3]</td> <td>mem_we_n[2]</td> <td>mem_we_n[1]</td> <td>mem_we_n[0]</td> <td></td> </tr> <tr> <td>32-bit</td> <td>mem_we_n[3]</td> <td>mem_we_n[2]</td> <td>mem_we_n[1]</td> <td>mem_we_n[0]</td> <td></td> </tr> <tr> <td>16-bit</td> <td>Byte High Write Enable</td> <td>mem_addr[1]</td> <td>Not Used (Driven Low)</td> <td>Byte Low Write Enable</td> <td></td> </tr> <tr> <td>8-bit</td> <td>Not Used (Driven High)</td> <td>mem_addr[1]</td> <td>mem_addr[0]</td> <td>Byte Write Enable</td> <td></td> </tr> </tbody> </table> <p>mem_addr[22] Alternate function: reset_boot_mode[1]. mem_addr[21] Alternate function: reset_boot_mode[0]. mem_addr[20] Alternate function: reset_pci_host_mode. mem_addr[19] Alternate function: modebit [9]. mem_addr[18] Alternate function: modebit [8]. mem_addr[17] Alternate function: modebit [7]. mem_addr[16] Alternate function: sdram_addr[16]. mem_addr[15] Alternate function: sdram_addr[15]. mem_addr[14] Alternate function: sdram_addr[14]. mem_addr[13] Alternate function: sdram_addr[13]. mem_addr[11] Alternate function: sdram_addr[11]. mem_addr[10] Alternate function: sdram_addr[10]. mem_addr[9] Alternate function: sdram_addr[9]. mem_addr[8] Alternate function: sdram_addr[8]. mem_addr[7] Alternate function: sdram_addr[7]. mem_addr[6] Alternate function: sdram_addr[6]. mem_addr[5] Alternate function: sdram_addr[5]. mem_addr[4] Alternate function: sdram_addr[4]. mem_addr[3] Alternate function: sdram_addr[3]. mem_addr[2] Alternate function: sdram_addr[2].</p>	Port Width	Pin Signals	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]	DMA (32-bit)	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]		32-bit	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]		16-bit	Byte High Write Enable	mem_addr[1]	Not Used (Driven Low)	Byte Low Write Enable		8-bit	Not Used (Driven High)	mem_addr[1]	mem_addr[0]	Byte Write Enable	
Port Width	Pin Signals	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																													
DMA (32-bit)	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																														
32-bit	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																														
16-bit	Byte High Write Enable	mem_addr[1]	Not Used (Driven Low)	Byte Low Write Enable																														
8-bit	Not Used (Driven High)	mem_addr[1]	mem_addr[0]	Byte Write Enable																														
mem_cs_n[5:0]	Output	H	Low	Memory Chip Select Negated Recommend an external pull-up. Signals that a Memory Bank is actively selected.																														
mem_oe_n	Output	H	High	Memory Output Enable Negated Recommend an external pull-up. Signals that a Memory Bank can output its data lines onto the cpu_ad bus.																														
mem_we_n[3:0]	Output	H	High	Memory Write Enable Negated Bus Signals which bytes are to be written during a memory transaction. Bits act as Byte Enable and mem_addr[1:0] signals for 8-bit or 16-bit wide addressing.																														

Table 1 Pin Descriptions (Part 1 of 6)

Name	Type	Reset State Status	Drive Strength Capability	Description
pci_req_n[2]	Input	Z	—	PCI Bus Request #2 Negated Requires an external pull-up. Host mode: pci_req_n[2] is an input indicating a request from an external device. Satellite mode: used as pci_idsel pin which selects this device during a configuration read or write. Alternate function: pci_idsel (satellite).
pci_req_n[1]	Input	Z	—	PCI Bus Request #1 Negated Requires external pull-up. Host mode: pci_req_n[1] is an input indicating a request from an external device. Alternate function: Unused (satellite).
pci_req_n[0]	I/O	Z	High	PCI Bus Request #0 Negated Requires an external pull-up for burst mode. Host mode: pci_req_n[0] is an input indicating a request from an external device. Satellite mode: pci_req_n[0] is an output indicating a request from this device.
pci_gnt_n[2]	Output	Z ¹	High	PCI Bus Grant #2 Negated Recommend an external pull-up. Host mode: pci_gnt_n[2] is an output indicating a grant to an external device. Satellite mode: pci_gnt_n[2] is used as the pci_inta_n output pin. External pull-up is required. Alternate function: pci_inta_n (satellite).
pci_gnt_n[1] / pci_eeprom_cs	I/O	X for 1 pci clock then H ²	High	PCI Bus Grant #1 Negated Recommend external pull-up. Host mode: pci_gnt_n[1] is an output indicating a grant to an external device. Satellite mode: Used as pci_eeprom_cs output pin for Serial Chip Select for loading PCI Configuration Registers in the RC32333 Reset Initialization Vector PCI boot mode. Defaults to the output direction at reset time. 1st Alternate function: pci_eeprom_cs (satellite). 2nd Alternate function: PIO[7].
pci_gnt_n[0]	I/O	Z	High	PCI Bus Grant #0 Negated Host mode: pci_gnt_n[0] is an output indicating a grant to an external device. Recommend external pull-up. Satellite mode: pci_gnt_n[0] is an input indicating a grant to this device. Requires external pull-up.
pci_inta_n	Output Open-collec- tor	Z	PCI	PCI Interrupt #A Negated Uses pci_gnt_n[2]. See the PCI subsection.
pci_lock_n	Input		—	PCI Lock Negated Driven by the Bus Master to indicate that an exclusive operation is occurring.

¹ Z in host mode; L in satellite non-boot mode; Z in satellite boot mode.² H in host mode, L in satellite non-boot and boot modes. X = unknown.

SDRAM Control Interface

sdram_addr_12	Output	L	High	SDRAM Address Bit 12 and Precharge All SDRAM mode: Provides SDRAM address bit 12 (10 on the SDRAM chip) during row address and "pre-charge all" signal during refresh, read and write command.
sdram_ras_n	Output	H	High	SDRAM RAS Negated SDRAM mode: Provides SDRAM RAS control signal to all SDRAM banks.
sdram_cas_n	Output	H	High	SDRAM CAS Negated SDRAM mode: Provides SDRAM CAS control signal to all SDRAM banks.
sdram_we_n	Output	H	High	SDRAM WE Negated SDRAM mode: Provides SDRAM WE control signal to all SDRAM banks.
sdram_cke	Output	H	High	SDRAM Clock Enable SDRAM mode: Provides clock enable to all SDRAM banks.

Table 1 Pin Descriptions (Part 3 of 6)

Name	Type	Reset State Status	Drive Strength Capability	Description
sdram_cs_n[3:0]	Output	H	High	SDRAM Chip Select Negated Bus Recommend an external pull-up. SDRAM mode: Provides chip select to each SDRAM bank. SODIMM mode: Provides upper select byte enables [7:4].
sdram_s_n[1:0]	Output	H	High	SDRAM SODIMM Select Negated Bus SDRAM mode: Not used. SDRAM SODIMM mode: Upper and lower chip selects.
sdram_bemask_n[3:0]	Output	H	High	SDRAM Byte Enable Mask Negated Bus (DQM) SDRAM mode: Provides byte enables for each byte lane of all DRAM banks. SODIMM mode: Provides lower select byte enables [3:0].
sdram_245_oe_n	Output	H	Low	SDRAM FCT245 Output Enable Negated Recommend an external pull-up. SDRAM mode: Controls output enable to optional FCT245 transceiver bank by asserting during both reads and writes to any DRAM bank.
sdram_245_dt_r_n	Output	Z	High	SDRAM FCT245 Direction Transmit/Receive Recommend an external pull-up. Uses cpu_dt_r_n. See CPU Core Specific Signals below.
On-Chip Peripherals				
dma_ready_n[0]	I/O	Z	Low	DMA Ready Negated Bus Requires an external pull-up. Ready mode: Input pin for general purpose DMA channel 0 that can initiate the next datum in the current DMA descriptor frame. Done mode: Input pin for general purpose DMA channel 0 that can terminate the current DMA descriptor frame. dma_ready_n[0] 1st Alternate function PIO[0]; 2nd Alternate function: dma_done_n[0].
pio[7:0]	I/O	See related pins	Low	Programmable Input/Output General purpose pins that can each can be configured as a general purpose input or general purpose output. These pins are multiplexed with other pin functions: pci_gnt_n[1] (pci_eeprom_cs), spi_mosi, spi_sck, spi_ss_n, spi_miso, uart_rx[0], uart_tx[0], dma_ready_n[0]. Note that pci_gnt_n[1], spi_mosi, spi_sck, and spi_ss_n default to outputs at reset time. The others default to inputs.
uart_rx[0]	I/O	Z	Low	UART Receive Data Bus UART mode: UART channel receive data. uart_rx[0] Alternate function: PIO[2].
uart_tx[0]	I/O	Z	Low	UART Transmit Data Bus Recommend an external pull-up. UART mode: UART channel send data. Note that this pin defaults to an input at reset time and must be programmed via the PIO interface before being used as a UART output. uart_tx[0] Alternate function: PIO[1].
spi_mosi	I/O	L	Low	SPI Data Output Serial mode: Output pin from RC32333 as an Input to a Serial Chip for the Serial data input stream. In PCI satellite mode, acts as an Output pin from RC32333 that connects as an Input to a Serial Chip for the Serial data input stream for loading PCI Configuration Registers in the RC32333 Reset Initialization Vector PCI boot mode. 1st Alternate function: PIO[6]. Defaults to the output direction at reset time. 2nd Alternate function: pci_eeprom_mdo.
spi_miso	I/O	Z	Low	SPI Data Input Serial mode: Input pin to RC32333 from the Output of a Serial Chip for the Serial data output stream. In PCI satellite mode, acts as an Input pin from RC32333 that connects as an output to a Serial Chip for the Serial data output stream for loading PCI Configuration Registers in the RC32333 Reset Initialization Vector PCI boot mode. Defaults to input direction at reset time. 1st Alternate function: PIO[3]. 2nd Alternate function: pci_eeprom_mdi.

Table 1 Pin Descriptions (Part 4 of 6)

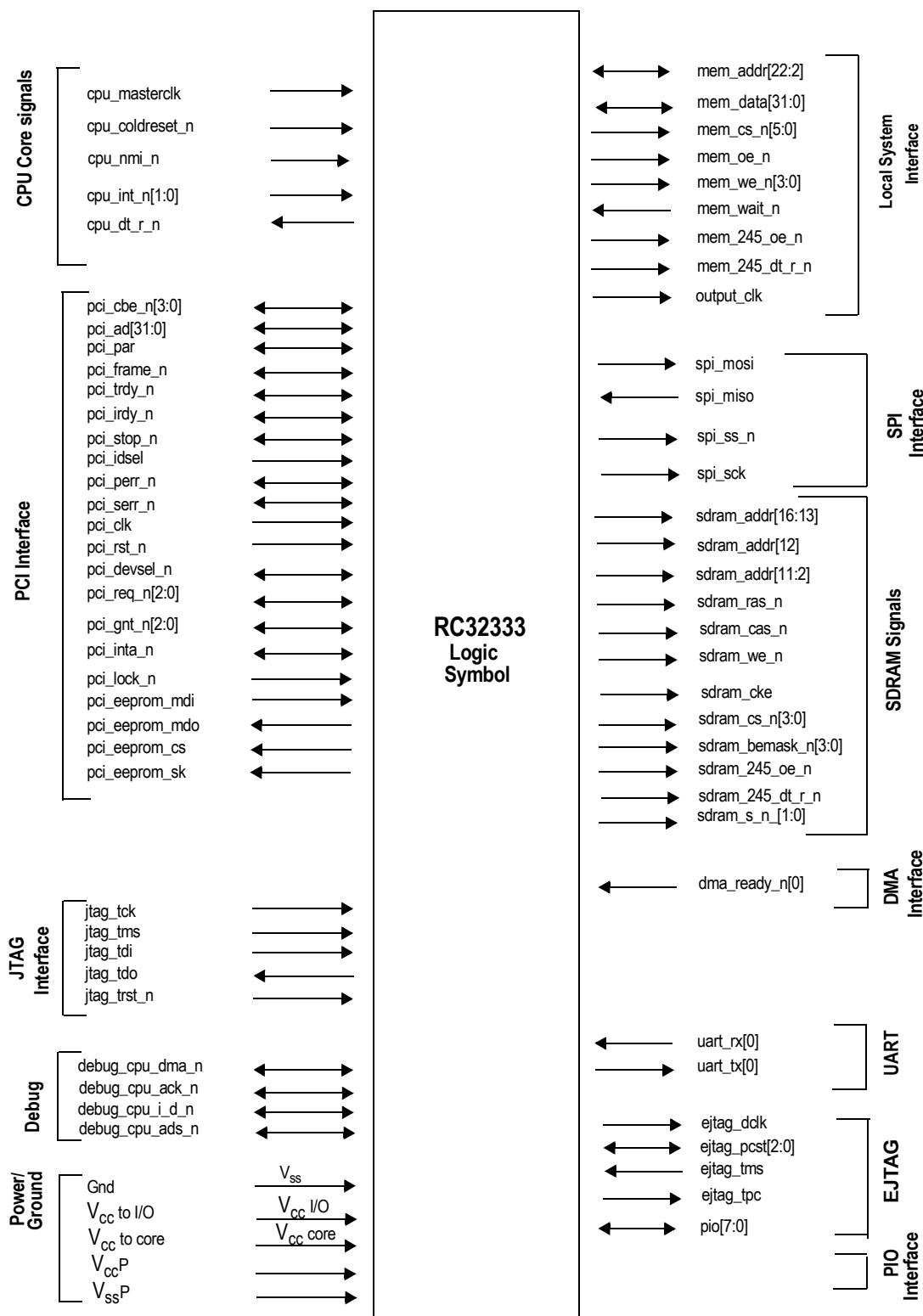
Name	Type	Reset State Status	Drive Strength Capability	Description
eitag_pcst[2:0]	I/O	Z	Low	EJTAG PC Trace Status Information 111 (STL) Pipe line Stall 110 (JMP) Branch/Jump forms with PC output 101 (BRT) Branch/Jump forms with no PC output 100 (EXP) Exception generated with an exception vector code output 011 (SEQ) Sequential performance 010 (TST) Trace is outputted at pipeline stall time 001 (TSQ) Trace trigger output at performance time 000 (DBM) Run Debug Mode Alternate function: modebit[2:0].
eitag_tms	Input		—	EJTAG Test Mode Select Requires an external pull-up. The ejtag_tms is sampled on the rising edge of jtag_tck.

Debug Signals

debug_cpu_dma_n	I/O	Z	Low	Debug CPU versus DMA Negated De-assertion high during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction was generated from the CPU. Assertion low during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction was generated from DMA. Alternate function: modebit[6].
debug_cpu_ack_n	I/O	Z	Low	Debug CPU Acknowledge Negated Indicates either a data acknowledge to the CPU or DMA. Alternate function: modebit[4].
debug_cpu_ads_n	I/O	Z	Low	Debug CPU Address/Data Strobe Negated Assertion indicates that either a CPU or a DMA transaction is beginning and that the mem_data[31:4] bus has the current block address. Alternate function: modebit[5].
debug_cpu_i_d_n	I/O	Z	Low	Debug CPU Instruction versus Data Negated Assertion during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction is a CPU or DMA data transaction. De-assertion during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction is a CPU instruction transaction. Alternate function: modebit[3].

Table 1 Pin Descriptions (Part 6 of 6)

Logic Diagram — RC32333



pci_host_mode Settings

During cold reset initialization, the RC32333's PCI interface can be set to the Satellite or Host mode settings. When set to the Host mode, the CPU must configure the RC32333's PCI configuration registers, including the read-only registers. If the RC32333's PCI is in the PCI-boot mode Satellite mode, read-only configuration registers are loaded by the serial EEPROM.

Pin	Reset Boot Mode	Description	Value	Mode Settings
mem_addr[20]	PCI host mode	PCI is in satellite mode	1	PCI_satellite
		PCI is in host mode (typical system)	0	PCI_host

Table 4 RC32333 pci_host_mode Initialization Settings

Clock Parameters — RC32333

Ta Commercial = 0°C to +70°C; Ta Industrial = -40°C to +85°C

3.3V version: V_{cc} Core = +3.3V±5%; V_{cc} I/O = +3.3V±5%

2.5V version: V_{cc} Core = +2.5V±5%; V_{cc} I/O = +3.3V±5%

Parameter	Symbol	Test Conditions	RC32333 100MHz		RC32333 133MHz		RC32333 150MHz		Units
			Min	Max	Min	Max	Min	Max	
cpu_masterclock HIGH	t _{MCHIGH}	Transition ≤ 2ns	8	—	6.75	—	6	—	ns
cpu_masterclock LOW	t _{MCLOW}	Transition ≤ 2ns	8	—	6.75	—	6	—	ns
cpu_masterclock period ¹ - 3.3V ver.	t _{MCP}	—	20	66.6	15	66.6	13.33	66.6	ns
cpu_masterclock period ¹ - 2.5V ver.	t _{MCP}	—	20	40.0	15	40.0	13.33	40.0	ns
cpu_masterclock Rise & Fall Time ²	t _{MCRise} , t _{MCFall}	—	—	3	—	3	—	3	ns
cpu_masterclock Jitter	t _{JITTER}	—	—	± 250	—	± 250	—	± 200	ps
pci_clk Rise & Fall Time	t _{PCRise} , t _{PCFall}	PCI 2.2	—	1.6	—	1.6	—	1.6	ns
pci_clk Period ¹	t _{PCP}	—	20	—	20	—	20	—	ns
jtag_tck Rise & Fall Time	t _{JCRise} , t _{JCFall}	—	—	5	—	5	—	5	ns
eitag_dck period	t _{DCK} , t ₁₁	—	10	—	10	—	10	—	ns
jtag_tck clock period	t _{TCK} , t ₃	—	100	—	100	—	100	—	ns
eitag_dck High, Low Time	t _{DCK} High, t ₉ t _{DCK} Low, t ₁₀	—	4	—	4	—	4	—	ns
eitag_dck Rise, Fall Time	t _{DCK} Rise, t ₉ t _{DCK} Fall, t ₁₀	—	—	1	—	1	—	1	ns
output_clk ³	t _{DO21}	—	N/A	N/A	N/A	N/A	N/A	N/A	—
cpu_coldreset_n Asserted during power-up	—	power-on sequence	120	—	120	—	120	—	ms
cpu_coldreset_n Rise Time	t _{CRRise}	—	—	5	—	5	—	5	ns

Table 5 Clock Parameters - RC32333

1. cpu_masterclock frequency should never be below pci_clk frequency if PCI interface is used.

2. Rise and Fall times are measured between 10% and 90%.

3. Output_clk should not be used in a system. Only the cpu_masterclock or its derivative must be used to drive all the subsystems with designs based on the RC3233x systems. Refer to the RC3233x Device Errata for more information.

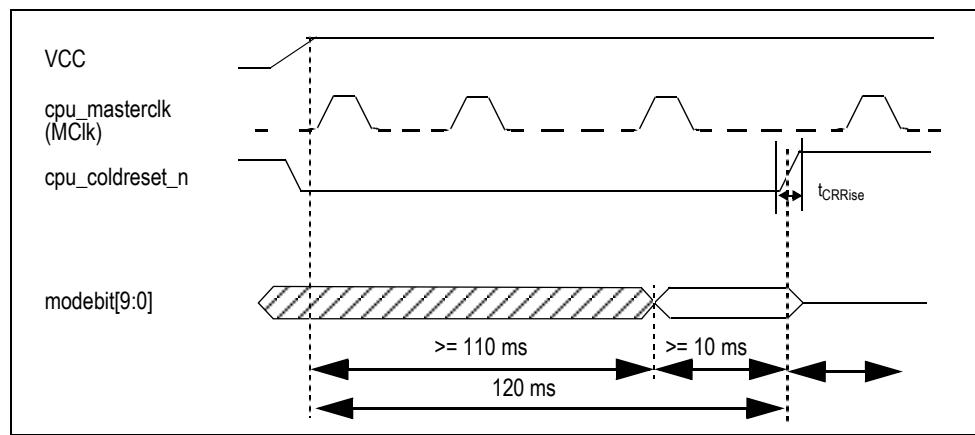
Reset Specification

Figure 3 Mode Configuration Interface Cold Reset Sequence

AC Timing Characteristics — RC32333

Ta Commercial = 0°C to +70°C; Ta Industrial = -40°C to +85°C

3.3V version: V_{cc} Core = +3.3V±5%; V_{cc} I/O = +3.3V±5%2.5V version: V_{cc} Core = +2.5V±5%; V_{cc} I/O = +3.3V±5%

Signal	Symbol	Reference Edge	RC32333¹ 100MHz		RC32333¹ 133MHz		RC32333¹ 150MHz		Units	User Manual Timing Diagram Reference
			Min	Max	Min	Max	Min	Max		

Local System Interface

mem_data[31:0] (data phase)	Tsu2	cpu_masterclk rising	6	—	5	—	4.8	—	ns	Chapter 9, Figures 9.2 and 9.3
mem_data[31:0] (data phase)	Thld2	cpu_masterclk rising	1.5	—	1.5	—	1.5	—	ns	
cpu_dt_r_n	Tdo3	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_data[31:0]	Tdo4	cpu_masterclk rising	—	12	—	10	—	9.3	ns	
mem_data[31:0] output hold time	Tdoh1	cpu_masterclk rising	1	—	1	—	1	—	ns	
mem_data[31:0] (tristate disable time)	Tdz	cpu_masterclk rising	—	12 ²	—	10 ²	—	9.3 ²	ns	
mem_data[31:0] (tristate to data time)	Tzd	cpu_masterclk rising	—	12 ²	—	10 ²	—	9.3 ²	ns	
mem_wait_n	Tsu6	cpu_masterclk rising	9	—	7	—	6	—	ns	
mem_wait_n	Thld8	cpu_masterclk rising	1	—	1	—	1	—	ns	
mem_addr[22:2]	Tdo5	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_cs_n[5:0]	Tdo6	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_oe_n, mem_245_oe_n	Tdo7	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_we_n[3:0]	Tdo7a	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_245_dt_r_n	Tdo8	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_addr[25:2] mem_cs_n[5:0] mem_oe_n, mem_we_n[3:0], mem_245_dt_r_n, mem_245_oe_n	Tdoh3	cpu_masterclk rising	1.5	—	1.5	—	1.5	—	ns	

PCI for 3.3V Device³

pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n	Tsu	pci_clk rising	3	—	3	—	3	—	ns	Chapter 10, Figures 10.6 through 10.8
pci_idsel, pci_req_n[2], pci_req_n[1], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_gnt_n[0]	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n ⁴	Thld	pci_clk rising	0	—	0	—	0	—	ns	

Table 6 AC Timing Characteristics - RC32333 (Part 1 of 4)

Signal	Symbol	Reference Edge	RC32333¹ 100MHz		RC32333¹ 133MHz		RC32333¹ 150MHz		Units	User Manual Timing Diagram Reference
			Min	Max	Min	Max	Min	Max		
pci_idsel, pci_req_n[2], pci_req_n[1], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Thld	pci_clk rising	0	—	0	—	0	—	ns	
pci_eeprom_mdi	Tsu	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	
pci_eeprom_mdi	Thld	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	
pci_eeprom_mdo, pci-eeprom_cs	Tdo	pci_clk rising, pci_eeprom_sk falling	—	15	—	12	—	10	ns	
pci_eeprom_sk	Tdo	pci_clk rising	—	15	—	12	—	10	ns	
pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n	Tdo	pci_clk rising	2	7.5	2	7.5	2	7.5	ns	
pci_req_n[0], pci_gnt_n[2], pci_gnt_n[1], pci_gnt_n[0], pci_inta_n	Tdo	pci_clk rising	2	7.5	2	7.5	2	7.5	ns	

PCI for 2.5V Device³

pci_ad[31:0], pci_par, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n ⁴	Tsu	pci_clk rising	3	—	3	—	3	—	ns	
pci_cbe_n[3:0], pci_frame_n, pci_trdy_n, pci_irdy_n	Tsu	pci_clk rising	4	—	4	—	4	—	ns	
pci_idsel, pci_req_n[2], pci_req_n[1], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_gnt_n[0]	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n ⁴	Thld	pci_clk rising	0	—	0	—	0	—	ns	
pci_idsel, pci_req_n[2], pci_req_n[1], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Thld	pci_clk rising	0	—	0	—	0	—	ns	
pci_eeprom_mdi	Tsu	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	
pci_eeprom_mdi	Thld	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	
pci_eeprom_mdo, pci-eeprom_cs	Tdo	pci_clk rising, pci_eeprom_sk falling	—	15	—	12	—	10	ns	
pci_eeprom_sk	Tdo	pci_clk rising	—	15	—	12	—	10	ns	

Table 6 AC Timing Characteristics - RC32333 (Part 2 of 4)

Signal	Symbol	Reference Edge	RC32333¹ 100MHz		RC32333¹ 133MHz		RC32333¹ 150MHz		Units	User Manual Timing Diagram Reference
			Min	Max	Min	Max	Min	Max		

Reset

mem_addr[19:17]	Tsu10	cpu_coldreset_n rising	10	—	10	—	10	—	ms	Chapter 19, Figures 19.8 and 19.9
mem_addr[19:17]	Thld10	cpu_coldreset_n rising	1	—	1	—	1	—	ns	
mem_addr[22:20]	Tsu22	cpu_masterclk rising	9	—	7	—	6	—	ns	
mem_addr[22:20]	Thld22	cpu_masterclk rising	1	—	1	—	1	—	ns	

Debug Interface

debug_cpu_dma_n, debug_cpu_ack_n, debug_cpu_ads_n, debug_cpu_i_d_n, ejtag_pcst[2:0]	Tsu20	cpu_coldreset_n rising	10	—	10	—	10	—	ms	Chapter 19, Figure 19.9 and Chapter 9, Figure 9.2
debug_cpu_dma_n, debug_cpu_ack_n, debug_cpu_ads_n, debug_cpu_i_d_n, ejtag_pcst[2:0]	Thld20	cpu_coldreset_n rising	1	—	1	—	1	—	ns	
debug_cpu_dma_n, debug_cpu_ack_n, debug_cpu_ads_n, debug_cpu_i_d_n	Tdo20	cpu_masterclk rising	—	15	—	12	—	10	ns	
debug_cpu_dma_n, debug_cpu_ack_n, debug_cpu_ads_n, debug_cpu_i_d_n	Tdoh20	cpu_masterclk rising	1	—	1	—	1	—	ns	

JTAG Interface

jtag_tms, jtag_tdi, jtag_trst_n	t ₅	jtag_tck rising	10	—	10	—	10	—	ns	See Figure 4 below.
jtag_tms, jtag_tdi, jtag_trst_n	t ₆	jtag_tck rising	10	—	10	—	10	—	ns	
jtag_tdo	t ₄	jtag_tck falling	—	10	—	10	—	10	ns	

EJTAG Interface

ejtag_tms	t ₅	jtag_tck rising	4	—	4	—	4	—	ns	See Figure 4 below.
ejtag_tms	t ₆	jtag_clk rising	2	—	2	—	2	—	ns	
jtag_tdo Output Delay Time	t _{TDODO} , t ₄	jtag_tck falling	—	6	—	6	—	6	ns	
jtag_tdi Input Setup Time	t _{TDIS} , t ₅	jtag_tck rising	4	—	4	—	4	—	ns	
jtag_tdi Input Hold Time	t _{TDIH} , t ₆	jtag_tck rising	2	—	2	—	2	—	ns	
jtag_trst_n Low Time	t _{TRSTLow} , t ₁₂	—	100	—	100	—	100	—	ns	
jtag_trst_n Removal Time	t _{TRSTR} , t ₁₃	jtag_tck rising	3	—	3	—	3	—	ns	
ejtag_tpc Output Delay Time	t _{TPCDO} , t ₈	ejtag_dclk rising	-1	3	-1	3	-1	3	ns	
ejtag_pcst Output Delay Time	t _{PCSTDO} , t ₇	ejtag_dclk rising	-1	3	-1	3	-1	3	ns	

Table 6 AC Timing Characteristics - RC32333 (Part 4 of 4)

1. At all pipeline frequencies.

2. Guaranteed by design.

3. This PCI interface conforms to the PCI Local Bus Specification, Rev 2.2 at 33MHz.

4. pci_RST_n is tested per PCI 2.2 as an asynchronous signal.

Standard EJTAG Timing — RC32333

Figure 4 represents the timing diagram for the EJTAG interface signals.

The standard JTAG connector is a 10-pin connector providing 5 signals and 5 ground pins. For Standard EJTAG, a 24-pin connector has been chosen providing 12 signals and 12 ground pins. This guarantees elimination of noise problems by incorporating signal-ground type arrangement. Refer to the RC3233x User Reference Manual for connector pinout and mechanical specifications.

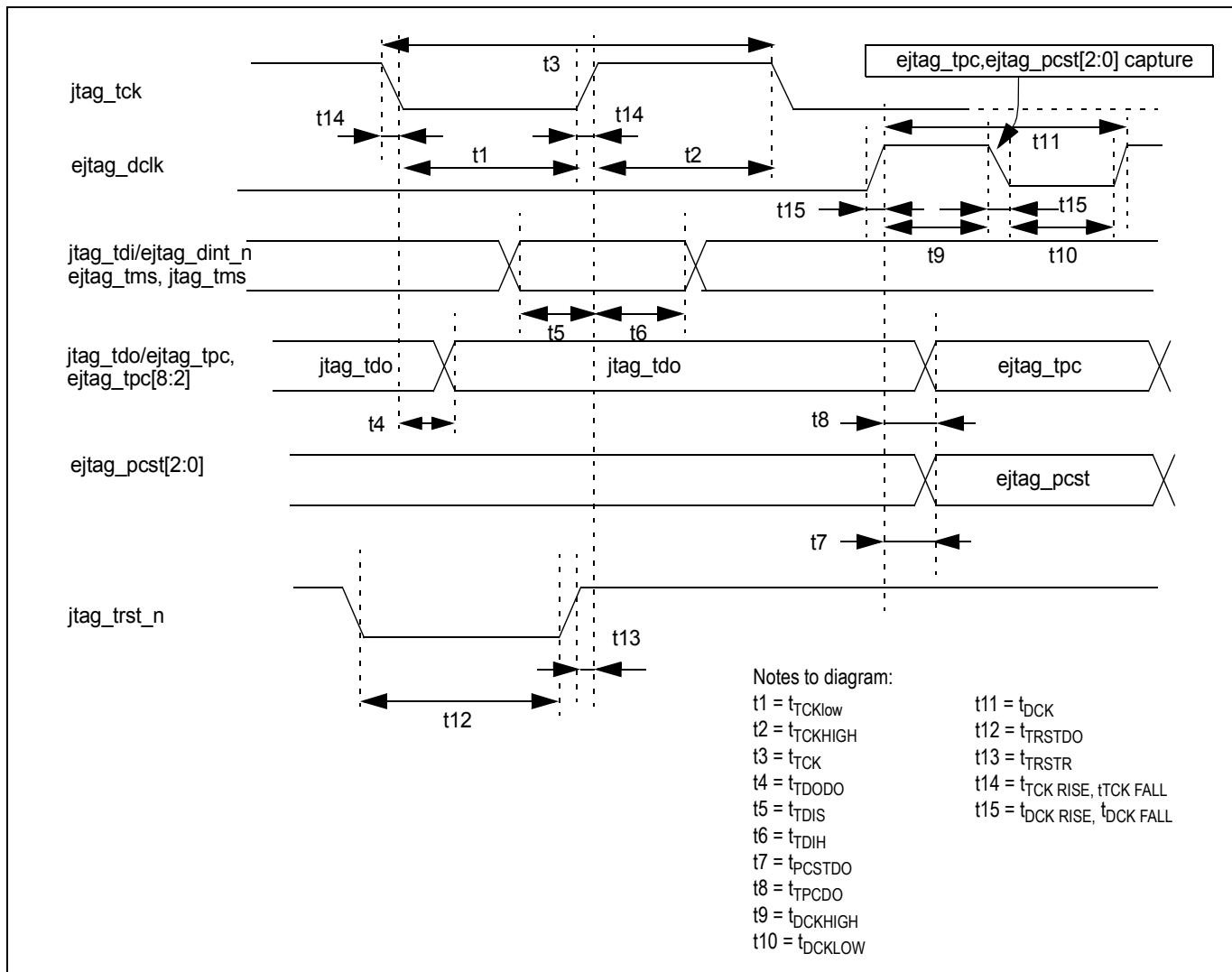
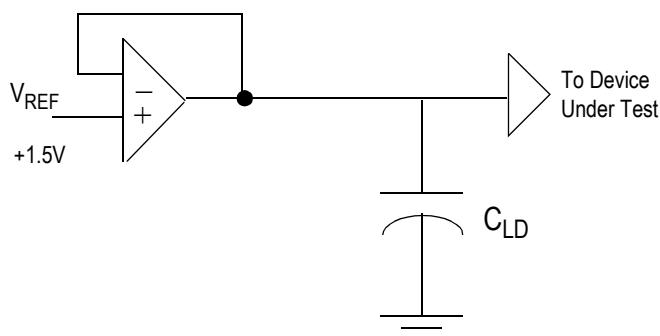


Figure 4 Standard EJTAG Timing

Output Loading for AC Testing



Signal	C_{ld}
All High Drive Signals	50 pF
All Low Drive Signals	25 pF

Figure 5 Output Loading for AC Testing

Note: PCI pins have been correlated to PCI 2.2.

Recommended Operation Temperature and Supply Voltage

3.3V Device

Grade	Ambient Temperature	Gnd	$V_{cc\,IO}$	$V_{cc\,Core}$	$V_{cc\,P}$
Commercial	0°C to +70°C Ambient	0V	3.3V±5%	3.3V±5%	3.3V±5%
Industrial	-40°C to +85°C Ambient	0V	3.3V±5%	3.3V±5%	3.3V±5%

Table 7 Temperature and Voltage — 3.3V Device

2.5V Device

Grade	Ambient Temperature	Gnd	$V_{cc\,IO}$	$V_{cc\,Core}$	$V_{cc\,P}$
Commercial	0°C to +70°C Ambient	0V	3.3V±5%	2.5V±5%	2.5V±5%
Industrial	-40°C to +85°C Ambient	0V	3.3V±5%	2.5V±5%	2.5V±5%

Table 8 Temperature and Voltage — 2.5V Device

DC Electrical Characteristics — RC32333

Ta Commercial = 0°C to +70°C; Ta Industrial = -40°C to +85°C

3.3V version: V_{cc} Core = $+3.3V \pm 5\%$; V_{cc} I/O = $+3.3V \pm 5\%$

2.5V version: V_{cc} Core = $+2.5V \pm 5\%$; V_{cc} I/O = $+3.3V \pm 5\%$

	Parameter	RC32333¹		Pin Numbers	Conditions
		Minimum	Maximum		
Input Pads	V_{IL}	—	0.8V	52, 64, 95, 161, 162, 165, 167-170, 191	—
	V_{IH}	2.0V	—		—
LOW Drive Output-Pads	V_{OL}	—	0.4V	41-45, 48, 171, 172, 175, 176, 177-180, 185-190, 195-200, 207, 208	$ I_{OUT} = 6mA$
	V_{OH}	$V_{cc} - 0.4V$	—		$ I_{OUT} = 8mA$
	V_{IL}	—	0.8V		—
	V_{IH}	2.0V	—		—
HIGH Drive Output Pads	V_{OL}	—	0.4V	1- 5, 8, 13-15, 18-25, 28-35, 38-40, 49-51, 53- 57, 60, 61, 63, 65-67, 70-76, 79, 80, 83-87, 90-94, 153, 154, 156, 159, 166, 194, 201, 204, 205, 206	$ I_{OUT} = 7mA$
	V_{OH}	$V_{cc} - 0.4V$	—		$ I_{OUT} = 16mA$
	V_{IL}	—	0.8V		—
	V_{IH}	2.0V	—		—
PCI Drive Input Pads	V_{IL}	—	—	123, 155, 157, 158, 160	Per PCI 2.2
	V_{IH}	—	—		—
PCI Drive Output pads	V_{OL}	—	—	96, 97, 100-109, 112-119, 122, 124-129, 132-139, 142-149, 152	Per PCI 2.2
	V_{OH}	—	—		—
	V_{IL}	—	—		—
	V_{IH}	—	—		—
All Pads	C_{IN}	—	10pF	All input pads except 155 and 156	—
	C_{IN}^2	5pf	12pF	155	Per PCI 2.2
	C_{IN}^3		8pF	156	Per PCI 2.2
	C_{OUT}	—	10pF	All output pads	—
	I_{O_LEAK}	—	10 μ A	All non-internal pull-up pins	Input/Output Leakage
	I_{O_LEAK}	—	50 μ A	All internal pull-up pins	Input/Output Leakage

Table 9 DC Electrical Characteristics - RC32333

1. At all pipeline frequencies.

2. Applies only to pad 155.

3. Applies only to pad 156.

Capacitive Load Deration — RC32333

Refer to the IDT document [79RC32333 IBIS Model](#) which can be found on the company's web site at www.idt.com.

Power Curves

The following four graphs contain the simulated power curves that show power consumption at various bus frequencies. Figures 6 and 7 apply to the 3.3V device, while Figures 8 and 9 apply to the 2.5V device.

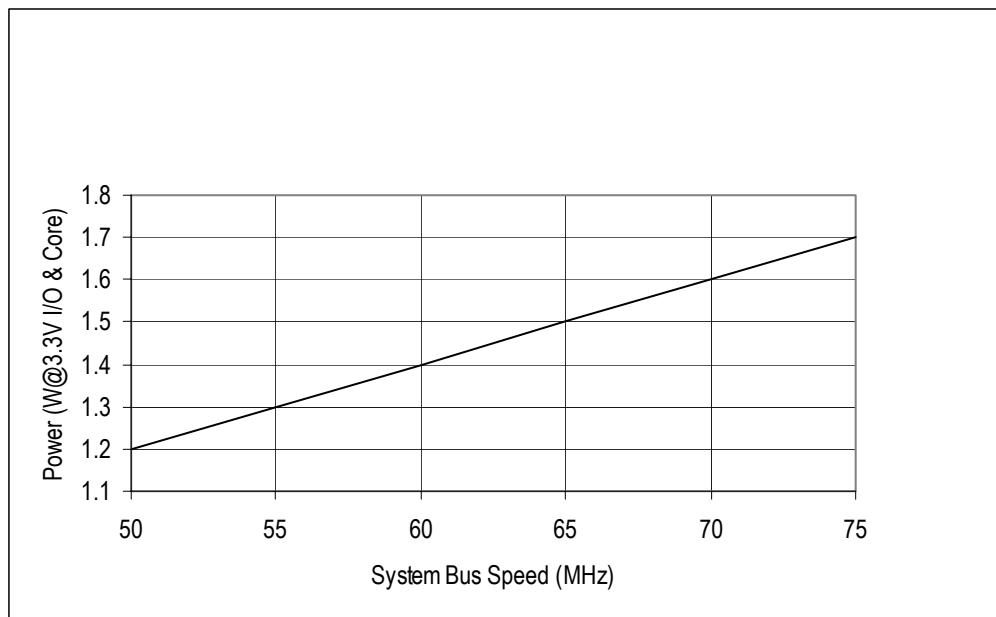


Figure 6 Typical Power Usage — RC32V333 Device

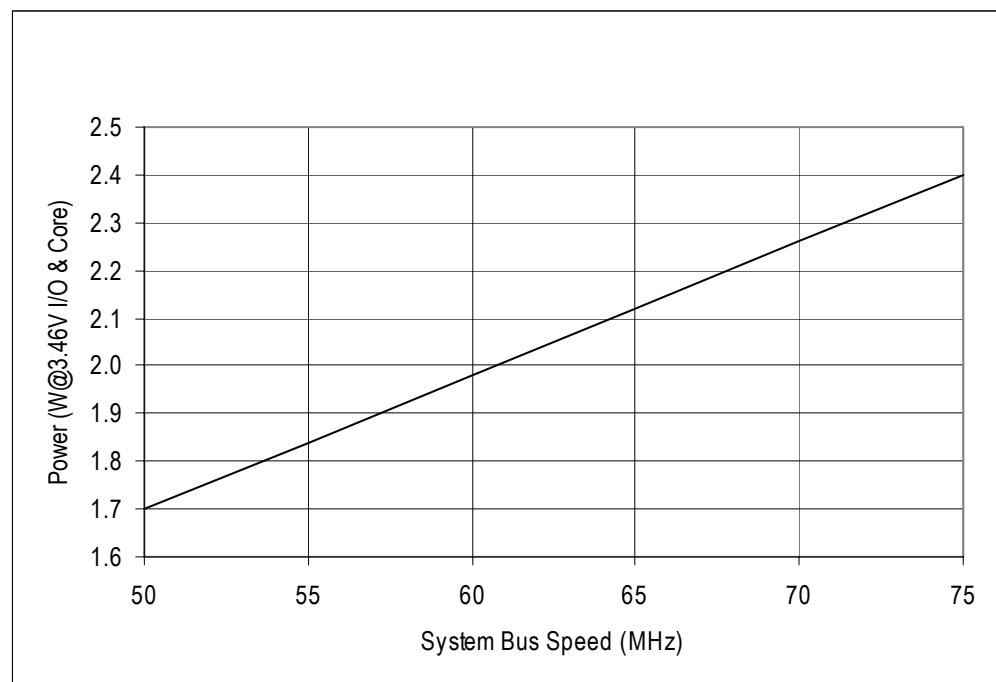


Figure 7 Maximum Power Usage — RC32V333 Device

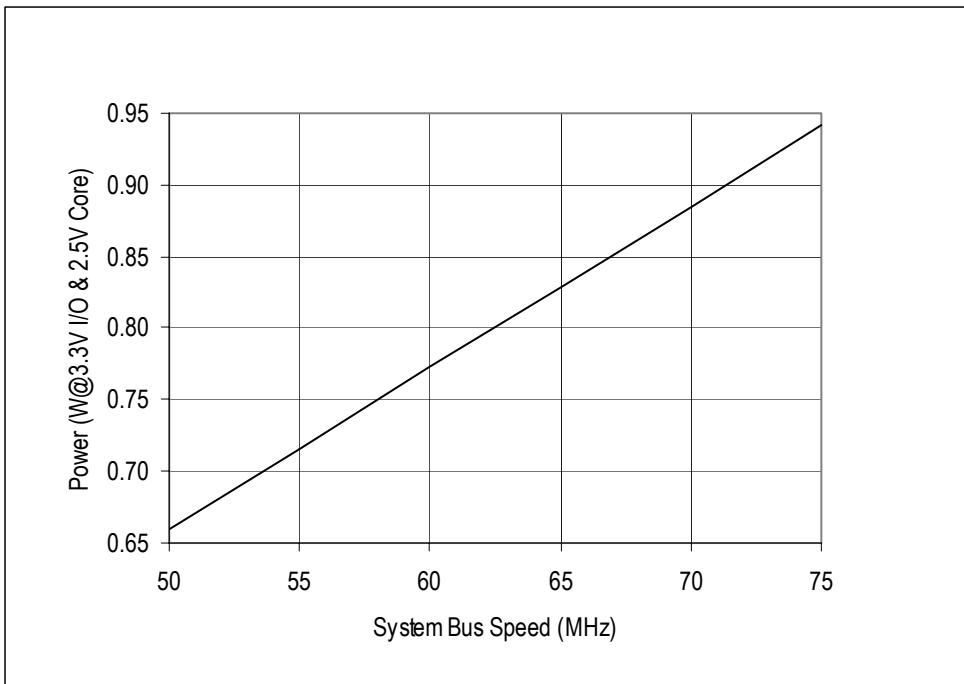


Figure 8 Typical Power Usage — RC32T333 Device

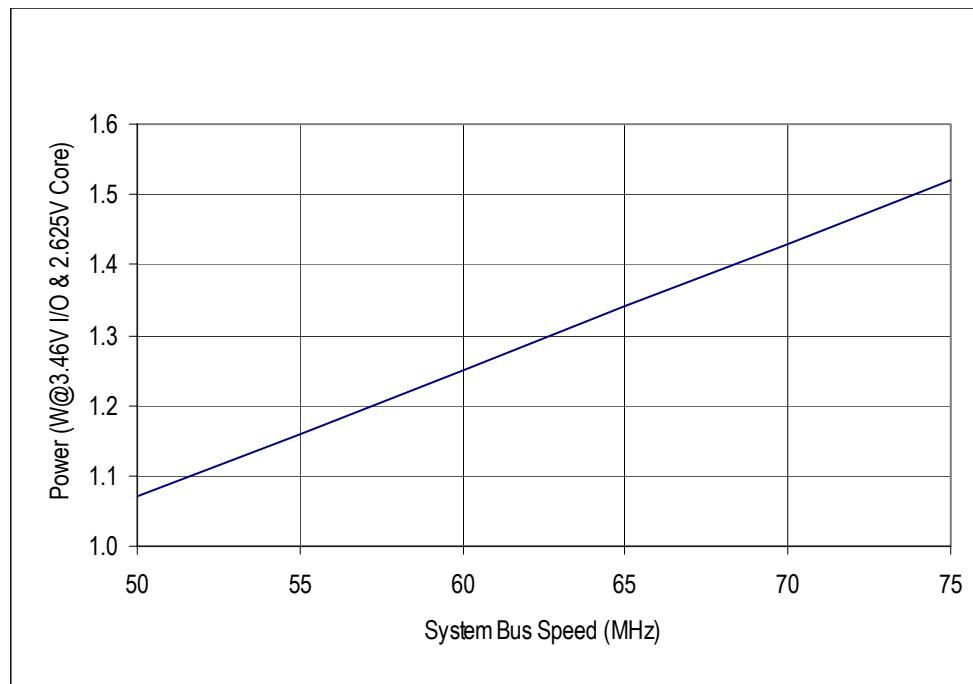


Figure 9 Maximum Power Usage — RC32T333 Device

Absolute Maximum Ratings

Symbol	Parameter	Min ¹	Max ¹	Unit
V _{cc} Core 3.3V Device	Supply Voltage	-0.3	4.0	V
V _{cc} Core 2.5V Device	Supply Voltage	-0.3	3.0	V
V _{cc} I/O	I/O Supply Voltage	-0.3	4.0	V
Vi 3.3V Device	Input Voltage	-0.3	5.5	V
Vi 2.5V Device	Input Voltage	-0.3	V _{CC} /I/O+0.3	V
Vimin	Input Voltage - undershoot ²	-0.6	—	V
Tstg	Storage Temperature	-40	125	degrees C

Table 12 Absolute Maximum Ratings

¹. Functional and tested operating conditions are given in Table 7. Absolute maximum ratings are stress ratings only, and functional operation is not guaranteed beyond recommended operating voltages and temperatures. Stresses beyond those listed may affect device reliability or cause permanent damage to the device.

². All PCI pads are fully compatible with PCI Specification version 2.2.

Package Pin-out — 208-PQFP for RC32333

The following table lists the pin numbers and signal names for the RC32333. Signal names ending with an _n are active when low.

Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt
1	sDRAM_245_oe_n		53	mem_data[12]		105	PCI_ad[7]		157	PCI_req_n[1]	
2	sDRAM_we_n		54	mem_data[19]		106	PCI_cbe_n[0]		158	PCI_req_n[2]	1
3	sDRAM_cas_n		55	mem_data[13]		107	PCI_ad[8]		159	PCI_gnt_n[2]	1
4	sDRAM_bmask_n[0]		56	mem_data[18]		108	PCI_ad[9]		160	PCI_rst_n	
5	sDRAM_bmask_n[1]		57	mem_data[14]		109	PCI_ad[10]		161	cpu_int_n[0]	
6	V _{ss}		58	V _{ss}		110	V _{ss}		162	cpu_int_n[1]	
7	V _{cc} I/O		59	V _{cc} I/O		111	V _{cc} I/O		163	V _{ss}	
8	sDRAM_cs_n[0]		60	mem_data[17]		112	PCI_ad[11]		164	V _{cc} I/O	
9	sDRAM_cs_n[1]		61	mem_data[16]		113	PCI_ad[12]		165	jtag_tdi	
10	sDRAM_ras_n		62	V _{cc} core		114	PCI_ad[13]		166	jtag_tdo	
11	sDRAM_s_n[0]		63	mem_data[15]		115	PCI_ad[14]		167	jtag_tms	
12	sDRAM_s_n[1]		64	cpu_masterclk		116	PCI_ad[15]		168	ejtag_tms	
13	mem_addr[2]	1	65	mem_data[31]		117	PCI_cbe_n[1]		169	jtag_tck	
14	mem_addr[3]	1	66	mem_data[0]		118	PCI_par		170	jtag_trst_n	
15	mem_addr[4]	1	67	mem_data[30]		119	PCI_serr_n		171	ejtag_pcst[0]	1
16	V _{ss}		68	V _{ss}		120	V _{ss}		172	ejtag_pcst[1]	1
17	V _{cc} I/O		69	V _{cc} I/O		121	V _{cc} I/O		173	V _{ss}	
18	mem_addr[5]	1	70	mem_data[1]		122	PCI_perr_n		174	V _{cc} I/O	

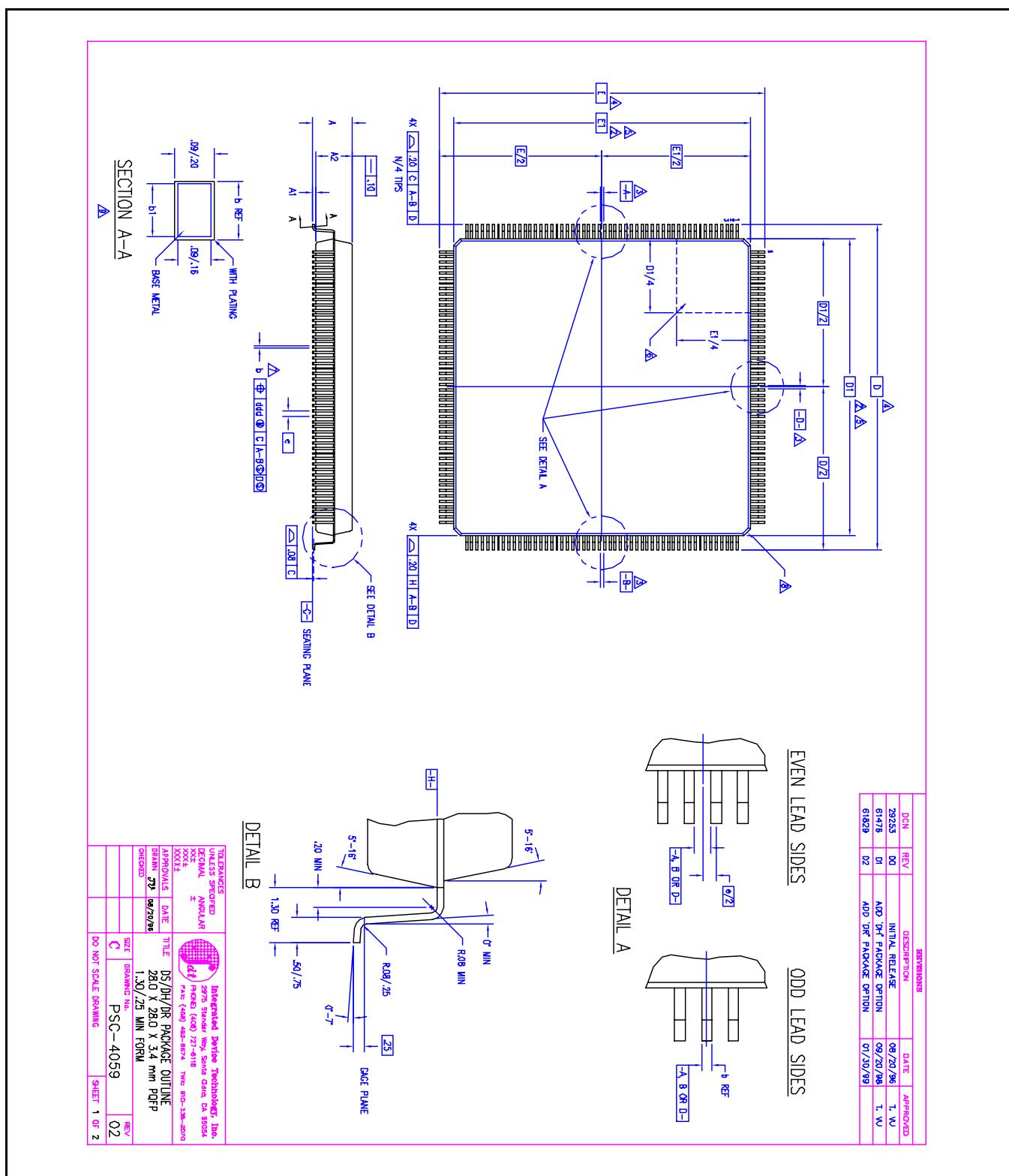
Table 13 RC32333 208-pin QFP Package Pin-Out (Part 1 of 2)

RC32333 Alternate Signal Functions

Pin	Alt #1	Alt #2	Pin	Alt #1	Alt #2	Pin	Alt #1	Alt #2
13	sDRAM_addr[2]		40	sDRAM_addr[16]		175	modebit[2]	
14	sDRAM_addr[3]		41	modebit[7]		177	modebit[3]	
15	sDRAM_addr[4]		42	modebit[8]		178	modebit[5]	
18	sDRAM_addr[5]		43	modebit[9]		179	modebit[4]	
19	sDRAM_addr[6]		44	reset_pci_host_mode		180	modebit[6]	
20	sDRAM_addr[7]		45	reset_boot_mode[0]		185	PIO[4]	
21	sDRAM_addr[8]		48	reset_boot_mode[1]		186	PIO[5]	pci_eeprom_sk
22	sDRAM_addr[9]		83	mem_245_dt_r_n	sDRAM_245_dt_r_n	187	PIO[3]	pci_eeprom_mdi
23	sDRAM_addr[10]		156	pci_eeprom_cs (satellite)	PIO[7]	188	PIO[6]	pci_eeprom_mdo
24	sDRAM_addr[11]		158	pci_idsel (satellite)		189	PIO[0]	dma_done_n[0]
35	sDRAM_addr[13]		159	pci_inta_n (satellite)		191	sDRAM_wait_n	mem_wait_n
38	sDRAM_addr[14]		171	modebit[0]		207	PIO[1]	
39	sDRAM_addr[15]		172	modebit[1]		208	PIO[2]	

Table 14 RC32333 Alternate Signal Functions

RC32333 Package Drawing — 208-pin PQFP



Ordering Information

79RCXX	V	DDD	SSS	PP	
Product Type	Operating Voltage	Device Type	CPU Frequency	Package	Temp range/ Process
					Blank = Commercial Temperature(0° C to +70° C Ambient)
					I = Industrial Temperature (-40° C to +85° C Ambient)
			100MHz 133MHz 150MHz	DH	DH = 208-pin PQFP
		333			
	V = 3.3V ±5% T = 2.5V ±5%				

79RC32 = 32-bit family product

Valid Combinations

3.3V Device

79RC32V333 - 100DH, 133DH, 150DH	Commercial
79RC32V333 - 100DHI, 133DHI, 150DHI	Industrial

2.5V Device

79RC32T333 - 100DH, 133DH, 150DH	Commercial
79RC32T333 - 100DHI, 133DHI, 150DHI	Industrial



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